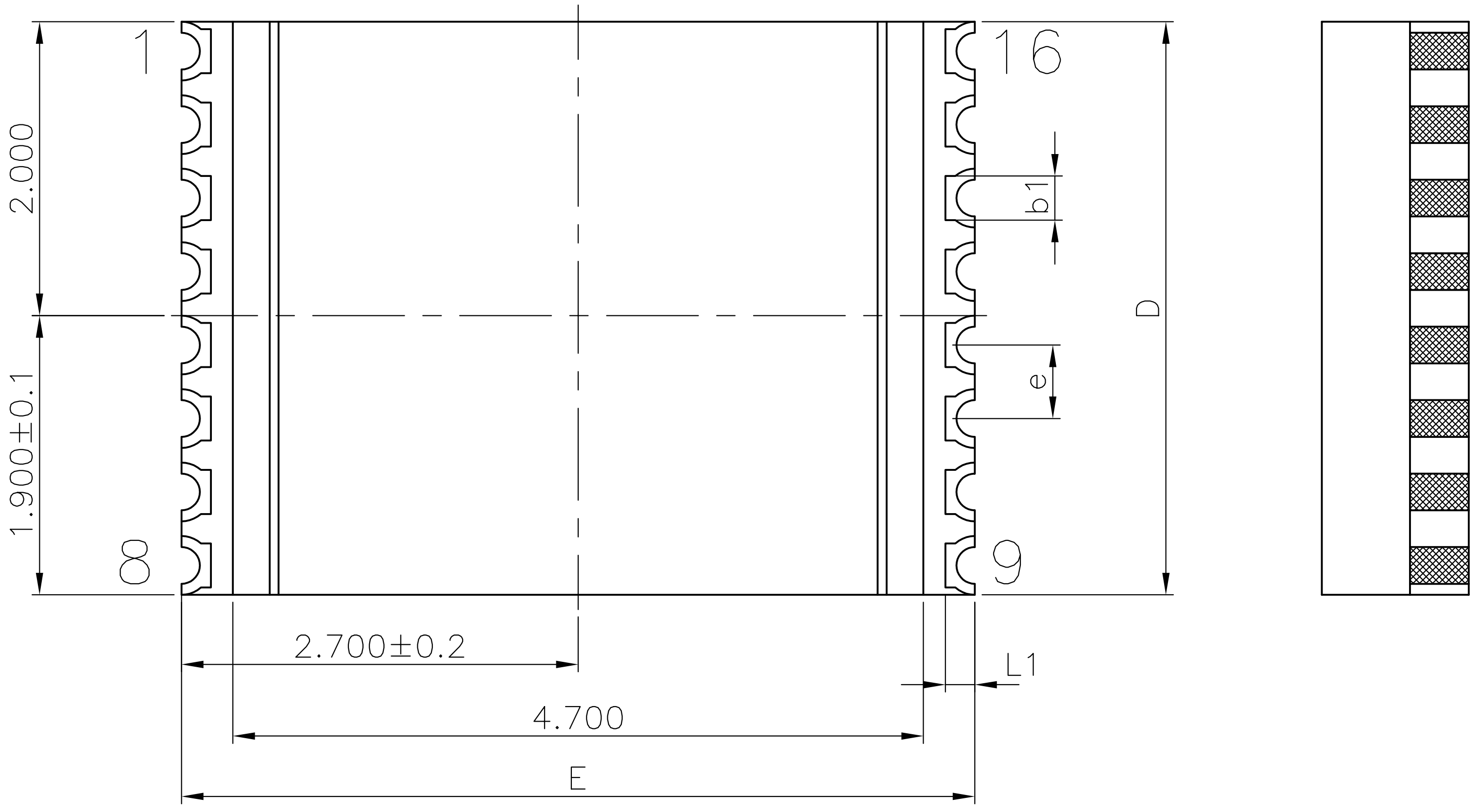
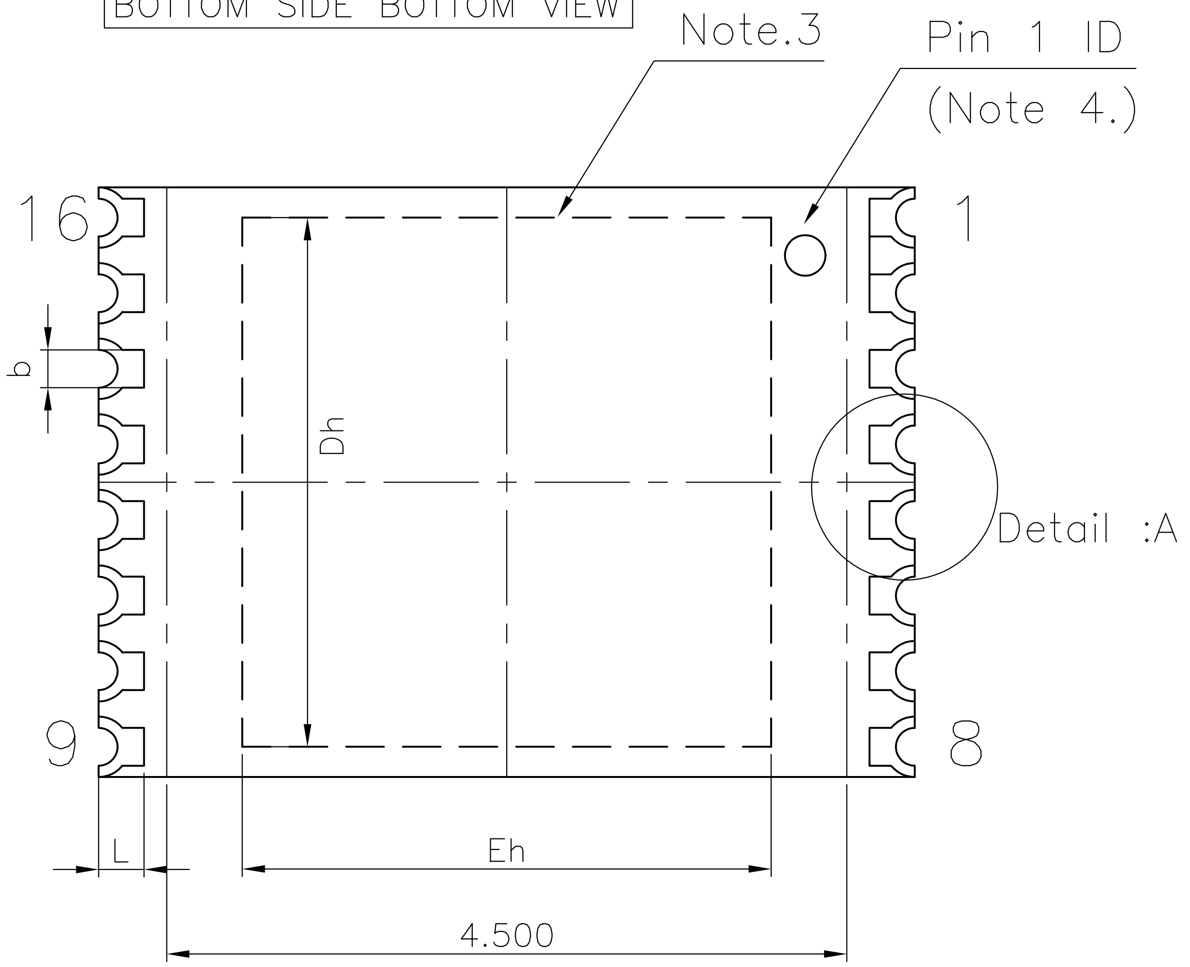
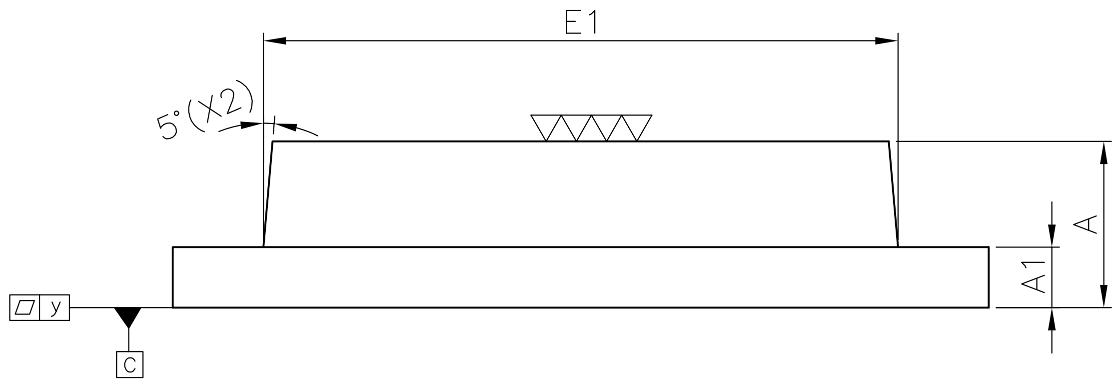
TOP SIDE TOP VIEW

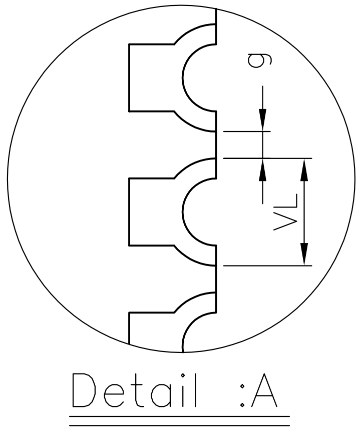


BOTTOM SIDE BOTTOM VIEW



SIDE VIEW





NOTE :

1. All dimensions are in millimeter.
2. The ID was made in solder mask layer of substrate.
3. The copper pad was covered with solder mask.
4. Without solder mask in the pin 1 ID circle.

SYMBOLS	DIMENSIONS IN MILLIMETERS		
	MIN	NOM	MAX
A	1.00	1.10	1.20
A1	——	0.40	——
D	3.80	3.90	4.00
E	5.30	5.40	5.50
E1	4.10	4.20	4.30
Dh	3.50	3.60	3.70
Eh	3.40	3.50	3.60
e	——	0.50	——
b	0.25	——	0.35
b1	0.25	——	0.35
L	0.20	0.30	0.40
L1	0.20	——	——
y	0.05	——	——
g	0.10	——	——
VL	——	0.40	——

CUSTOMER APPROVAL

APPROVED BY	DATE
DRAW BY: Sandy Sue	08/02/'06
CHECK BY: Kevin Liao	08/14/'06
APPROVAL: Jack Tu	08/14/'06
APPROVAL: Jack Tu	08/14/'06

LINGSEN 5-1 NAN 2ND ROAD T.E.P.Z
PRECISION IND., LTD TAICHUNG., TAIWAN R. O. C

TITLE:
COB 16L(5.4x3.9mm) package Outline Drawing

DWG. NO. PO-COB-025
REV. 0
UNIT : mm
SCALE : 20/1
SHEET 1 OF 1